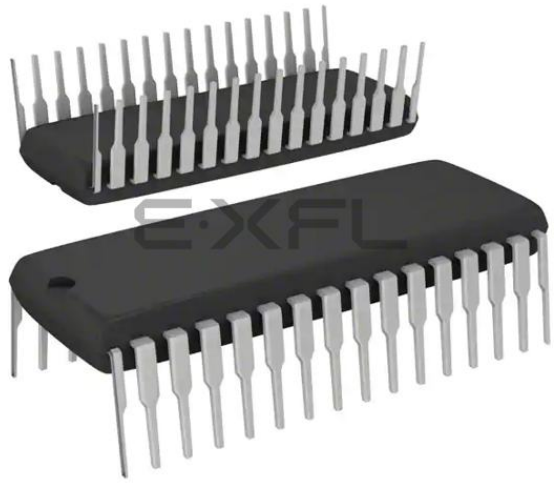

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	384 x 8
Voltage - Supply (Vcc/Vdd)	3.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	32-SDIP (0.400", 10.16mm)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st72f324bk2b6

5.3.5 Stack Pointer register (SP)

SP — Reset value: 01 FFh

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	1	SP7	SP6	SP5	SP4	SP3	SP2	SP1	SP0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

The Stack Pointer is a 16-bit register which is always pointing to the next free location in the stack. It is then decremented after data has been pushed onto the stack and incremented before data is popped from the stack (see *Figure 10*).

Since the stack is 256 bytes deep, the 8 most significant bits are forced by hardware. Following an MCU reset, or after a Reset Stack Pointer instruction (RSP), the Stack Pointer contains its reset value (the SP7 to SP0 bits are set) which is the stack higher address.

The least significant byte of the Stack Pointer (called S) can be directly accessed by an LD instruction.

Note: When the lower limit is exceeded, the Stack Pointer wraps around to the stack upper limit, without indicating the stack overflow. The previously stored information is then overwritten and therefore lost. The stack also wraps in case of an underflow.

The stack is used to save the return address during a subroutine call and the CPU context during an interrupt. The user may also directly manipulate the stack by means of the PUSH and POP instructions. In the case of an interrupt, the PCL is stored at the first location pointed to by the SP. Then the other registers are stored in the next locations as shown in *Figure 10*.

- When an interrupt is received, the SP is decremented and the context is pushed on the stack.
- On return from interrupt, the SP is incremented and the context is popped from the stack.

A subroutine call occupies two locations and an interrupt five locations in the stack area.

Figure 10. Stack manipulation example

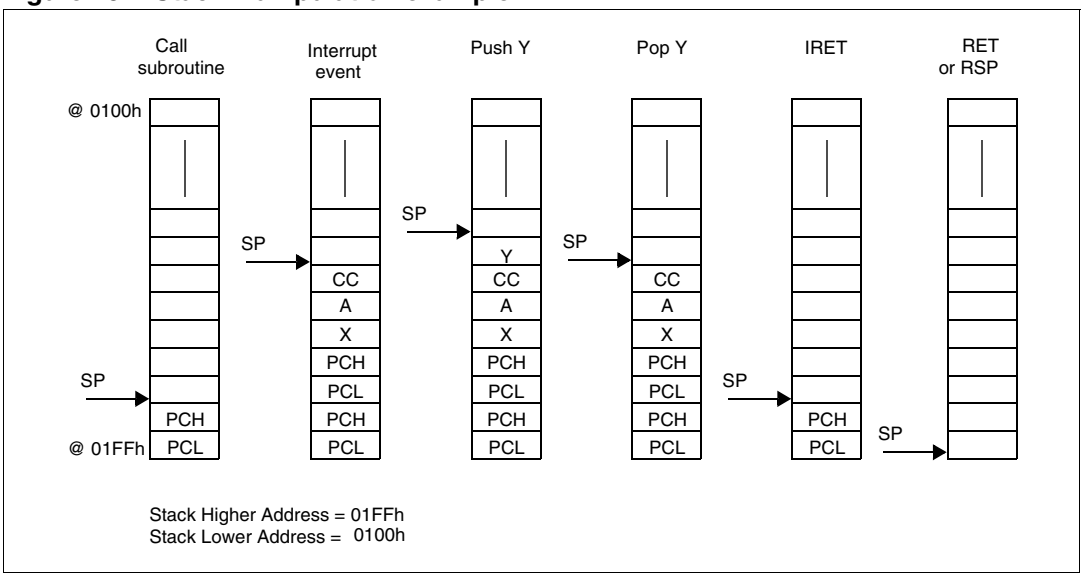


Figure 28. Halt timing overview

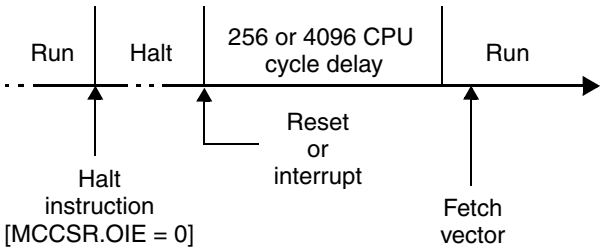
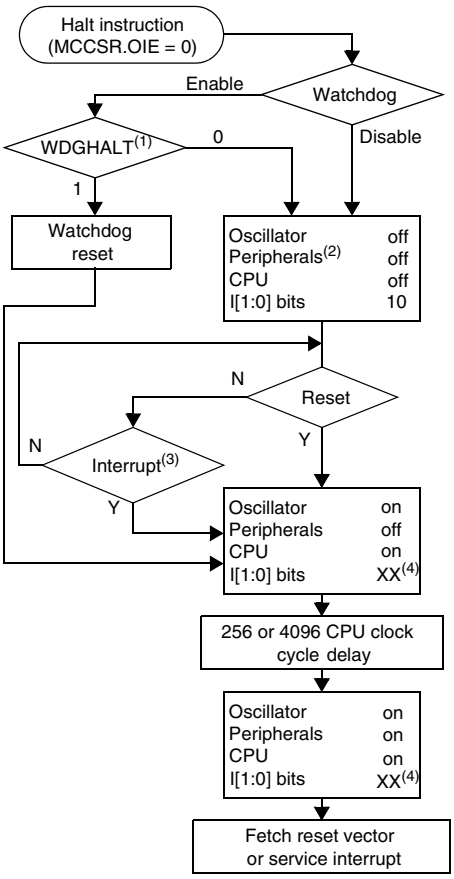


Figure 29. Halt mode flowchart



1. WDGHALT is an option bit. See *Section 14.1 on page 179* for more details.
2. Peripheral clocked with an external clock source can still be active.
3. Only some specific interrupts can exit the MCU from Halt mode (such as external interrupt). Refer to *Table 25: Interrupt mapping* for more details.
4. Before servicing an interrupt, the CC register is pushed on the stack. The I[1:0] bits of the CC register are set to the current software priority level of the interrupt routine and recovered when the CC register is popped.

Analog alternate function

When the pin is used as an ADC input, the I/O must be configured as floating input. The analog multiplexer (controlled by the ADC registers) switches the analog voltage present on the selected pin to the common analog rail which is connected to the ADC input.

It is recommended not to change the voltage level or loading on any port pin while conversion is in progress. Furthermore it is recommended not to have clocking pins located close to a selected analog pin.

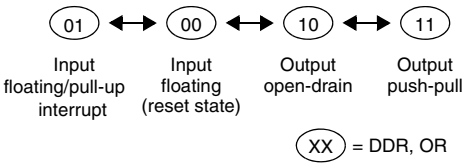
Warning: The analog input voltage level must be within the limits stated in the absolute maximum ratings.

9.3 I/O port implementation

The hardware implementation on each I/O port depends on the settings in the DDR and OR registers and specific feature of the I/O port such as ADC Input or true open drain.

Switching these I/O ports from one state to another should be done in a sequence that prevents unwanted side effects. Recommended safe transitions are illustrated in *Figure 31.* Other transitions are potentially risky and should be avoided, since they are likely to present unwanted side-effects such as spurious interrupt generation.

Figure 31. Interrupt I/O port state transitions



9.4 Low power modes

Table 30. Effect of low power modes on I/O ports

Mode	Description
Wait	No effect on I/O ports. External interrupts cause the device to exit from Wait mode.
Halt	No effect on I/O ports. External interrupts cause the device to exit from Halt mode.

9.5 Interrupts

The external interrupt event generates an interrupt if the corresponding configuration is selected with DDR and OR registers and the interrupt mask in the CC register is not active (RIM instruction).

10.1.5 Low power modes

Table 34. Effect of lower power modes on Watchdog

Mode	Description		
Slow	No effect on Watchdog		
Wait			
Halt	**OIE bit in MCCSR register**	**WDGHALT bit in option byte**	
	0	0	No Watchdog reset is generated. The MCU enters Halt mode. The Watchdog counter is decremented once and then stops counting and is no longer able to generate a watchdog reset until the MCU receives an external interrupt or a reset. If an external interrupt is received, the Watchdog restarts counting after 256 or 4096 CPU clocks. If a reset is generated, the Watchdog is disabled (reset state) unless Hardware Watchdog is selected by option byte. For application recommendations, see *Section 10.1.7* below.
	0	1	A reset is generated.
	1	x	No reset is generated. The MCU enters Active-halt mode. The Watchdog counter is not decremented. It stop counting. When the MCU receives an oscillator interrupt or external interrupt, the Watchdog restarts counting immediately. When the MCU receives a reset the Watchdog restarts counting after 256 or 4096 CPU clocks.

10.1.6 Hardware Watchdog option

If Hardware Watchdog is selected by option byte, the watchdog is always active and the WDGA bit in the WDGCR is not used. Refer to the option byte description in *Section 14.1: Flash devices*.

10.1.7 Using Halt mode with the WDG (WDGHALT option)

The following recommendation applies if Halt mode is used when the watchdog is enabled: Before executing the HALT instruction, refresh the WDG counter to avoid an unexpected WDG reset immediately after waking up the microcontroller.

10.1.8 Interrupts

None.

If the timer clock is an external clock, the formula is:

$$\Delta OCiR = \Delta t * f_{EXT}$$

Where:

Δt = Output compare period (in seconds)
f_{EXT} = External timer clock frequency (in hertz)

Clearing the output compare interrupt request (that is, clearing the OCF*i* bit) is done by:

1. Reading the SR register while the OCF*i* bit is set.
2. An access (read or write) to the OC*i*LR register.

The following procedure is recommended to prevent the OCF*i* bit from being set between the time it is read and the write to the OC*i*R register:

- Write to the OC*i*HR register (further compares are inhibited).
- Read the SR register (first step of the clearance of the OCF*i* bit, which may be already set).
- Write to the OC*i*LR register (enables the output compare function and clears the OCF*i* bit).

Note: 1 After a processor write cycle to the OCiHR register, the output compare function is inhibited until the OCiLR register is also written.

2 If the OCiE bit is not set, the OCMPi pin is a general I/O port and the OLVLi bit will not appear when a match is found but an interrupt could be generated if the OCIE bit is set.

3 In both internal and external clock modes, OCFi and OCMPi are set while the counter value equals the OCiR register value (see Figure 44 on page 83 for an example with $f_{CPU}/2$ and Figure 45 on page 83 for an example with $f_{CPU}/4$). This behavior is the same in OPM or PWM mode.

4 The output compare functions can be used both for generating external events on the OCMPi pins even if the input capture mode is also used.

5 The value in the 16-bit OCiR register and the OLVi bit should be changed after each successful comparison in order to control an output waveform or establish a new elapsed timeout.

Forced output compare capability

When the FOLV*i* bit is set by software, the OLVL*i* bit is copied to the OCMP*i* pin. The OLV*i* bit has to be toggled in order to toggle the OCMP*i* pin when it is enabled (OC*i*E bit = 1). The OCF*i* bit is then not set by hardware, and thus no interrupt request is generated.

The FOLVL*i* bits have no effect in both one pulse mode and PWM mode.

Table 55. SPICR register description

Bit	Name	Function
7	SPIE	Serial Peripheral Interrupt Enable This bit is set and cleared by software. 0: Interrupt is inhibited. 1: An SPI interrupt is generated whenever SPIF = 1, MODF = 1 or OVR = 1 in the SPICSR register.
6	SPE	Serial Peripheral Output Enable This bit is set and cleared by software. It is also cleared by hardware when, in master mode, $\overline{SS}$ = 0 (see *Master mode fault (MODF) on page 102*). The SPE bit is cleared by reset, so the SPI peripheral is not initially connected to the external pins. 0: I/O pins free for general purpose I/O 1: SPI I/O pin alternate functions enabled
5	SPR2	Divider Enable This bit is set and cleared by software and is cleared by reset. It is used with the SPR[1:0] bits to set the baud rate. Refer to *Table 56: SPI master mode SCK frequency*. 0: Divider by 2 enabled 1: Divider by 2 disabled *Note: This bit has no effect in slave mode.*
4	MSTR	Master mode This bit is set and cleared by software. It is also cleared by hardware when, in master mode, $\overline{SS}$ = 0 (see *Master mode fault (MODF) on page 102*). 0: Slave mode 1: Master mode. The function of the SCK pin changes from an input to an output and the functions of the MISO and MOSI pins are reversed.
3	CPOL	Clock Polarity This bit is set and cleared by software. This bit determines the idle state of the serial Clock. The CPOL bit affects both the master and slave modes. 0: SCK pin has a low level idle state 1: SCK pin has a high level idle state *Note: If CPOL is changed at the communication byte boundaries, the SPI must be disabled by resetting the SPE bit.*
2	CPHA	Clock Phase This bit is set and cleared by software. 0: The first clock transition is the first data capture edge. 1: The second clock transition is the first capture edge. *Note: The slave must have the same CPOL and CPHA settings as the master.*
1:0	SPR[1:0]	Serial clock frequency These bits are set and cleared by software. Used with the SPR2 bit, they select the baud rate of the SPI serial clock SCK output by the SPI in master mode (see *Table 56*). *Note: These 2 bits have no effect in slave mode.*

Table 56. SPI master mode SCK frequency

Serial clock	SPR2	SPR1	SPR0
$f_{CPU}/4$	1	0	0
$f_{CPU}/8$	0	0	0

Table 56. SPI master mode SCK frequency (continued)

Serial clock	SPR2	SPR1	SPR0
$f_{CPU}/16$	0	0	1
$f_{CPU}/32$	1	1	0
$f_{CPU}/64$	0	1	0
$f_{CPU}/128$	0	1	1

SPI control/status register (SPICSR)

SPICSR Reset value: 0000 0000 (00h)

7	6	5	4	3	2	1	0
SPIF	WCOL	OVR	MODF	Reserved	SOD	SSM	SSI
RO	RO	RO	RO	-	R/W	R/W	R/W

Table 57. SPICSR register description

Bit	Name	Function
7	SPIF	Serial peripheral data transfer flag This bit is set by hardware when a transfer has been completed. An interrupt is generated if SPIE = 1 in the SPICR register. It is cleared by a software sequence (an access to the SPICSR register followed by a write or a read to the SPIDR register). 0: Data transfer is in progress or the flag has been cleared 1: Data transfer between the device and an external device has been completed. *Note: While the SPIF bit is set, all writes to the SPIDR register are inhibited until the SPICSR register is read.*
6	WCOL	Write collision status This bit is set by hardware when a write to the SPIDR register is done during a transmit sequence. It is cleared by a software sequence (see *Figure 55*). 0: No write collision occurred 1: A write collision has been detected.
5	OVR	SPI Overrun error This bit is set by hardware when the byte currently being received in the shift register is ready to be transferred into the SPIDR register while SPIF = 1 (see *Overrun condition (OVR) on page 102*). An interrupt is generated if SPIE = 1 in SPICR register. The OVR bit is cleared by software reading the SPICSR register. 0: No overrun error 1: Overrun error detected
4	MODF	Mode fault flag This bit is set by hardware when the $\overline{SS}$ pin is pulled low in master mode (see *Master mode fault (MODF) on page 102*). An SPI interrupt can be generated if SPIE = 1 in the SPICSR register. This bit is cleared by a software sequence (An access to the SPICR register while MODF = 1 followed by a write to the SPICR register). 0: No master mode fault detected 1: A fault in master mode has been detected.
3	-	Reserved, must be kept cleared.

Clock deviation causes

The causes which contribute to the total deviation are:

- D_{TRA}: Deviation due to transmitter error (local oscillator error of the transmitter or the transmitter is transmitting at a different baud rate).
- D_{QUANT}: Error due to the baud rate quantization of the receiver.
- D_{REC}: Deviation of the local oscillator of the receiver: This deviation can occur during the reception of one complete SCI message assuming that the deviation has been compensated at the beginning of the message.
- D_{TCL}: Deviation due to the transmission line (generally due to the transceivers)

All the deviations of the system should be added and compared to the SCI clock tolerance:

$$D_{TRA} + D_{QUANT} + D_{REC} + D_{TCL} < 3.75\%$$

Noise error causes

See also the description of Noise error in *Receiver on page 113*.

Start bit

The Noise Flag (NF) is set during start bit reception if one of the following conditions occurs:

1. A valid falling edge is not detected. A falling edge is considered to be valid if the three consecutive samples before the falling edge occurs are detected as ‘1’ and, after the falling edge occurs, during the sampling of the 16 samples, if one of the samples numbered 3, 5 or 7 is detected as a ‘1’.
2. During sampling of the 16 samples, if one of the samples numbered 8, 9 or 10 is detected as a ‘1’.

Therefore, a valid Start bit must satisfy both the above conditions to prevent the Noise Flag from being set.

Data bits

The Noise Flag (NF) is set during normal data bit reception if the following condition occurs: During the sampling of 16 samples, if all three samples numbered 8, 9 and10 are not the same. The majority of the 8th, 9th and 10th samples is considered as the bit value.

Therefore, a valid Data bit must have samples 8, 9 and 10 at the same value to prevent the Noise Flag from being set.

Figure 60. Bit sampling in Reception mode

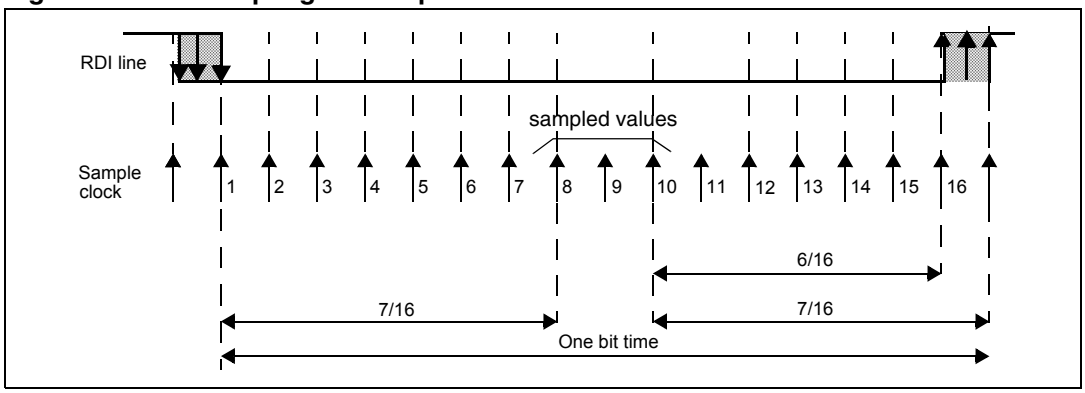


Table 71. ADCCSR register description (continued)

Bit	Name	Function
4	-	Reserved, must be kept cleared.
3:0	CH[3:0]	Channel selection These bits are set and cleared by software. They select the analog input to convert. 0000: Channel pin = AIN0 0001: Channel pin = AIN1 0010: Channel pin = AIN2 0011: Channel pin = AIN3 0100: Channel pin = AIN4 0101: Channel pin = AIN5 0110: Channel pin = AIN6 0111: Channel pin = AIN7 1000: Channel pin = AIN8 1001: Channel pin = AIN9 1010: Channel pin = AIN10 1011: Channel pin = AIN11 1100: Channel pin = AIN12 1101: Channel pin = AIN13 1110: Channel pin = AIN14 1111: Channel pin = AIN15 *Note: The number of channels is device dependent. Refer to Section 2: Pin description.*

ADC data register high (ADCDRH)

ADCDRH Reset value: 0000 0000 (00h)

7	6	5	4	3	2	1	0
D[9:2]							
RO							

Table 72. ADCDRH register description

Bit	Name	Function
7:0	D[9:2]	MSB of converted analog value

11 Instruction set

11.1 CPU addressing modes

The CPU features 17 different addressing modes which can be classified in 7 main groups (see *Table 75*).

Table 75. Addressing mode groups

Addressing mode	Example
Inherent	nop
Immediate	ld A,#$55
Direct	ld A,$55
Indexed	ld A,($55,X)
Indirect	ld A,([$55],X)
Relative	jrne loop
Bit operation	bset byte,#5

The CPU Instruction Set is designed to minimize the number of bytes required per instruction: To do so, most of the addressing modes may be divided in two submodes called long and short:

- Long addressing mode is more powerful because it can use the full 64 Kbyte address space, however it uses more bytes and more CPU cycles.
- Short addressing mode is less powerful because it can generally only access page zero (0000h - 00FFh range), but the instruction size is more compact, and faster. All memory to memory instructions use short addressing modes only (CLR, CPL, NEG, BSET, BRES, BTJT, BTJF, INC, DEC, RLC, RRC, SLL, SRL, SRA, SWAP)

The ST7 Assembler optimizes the use of long and short addressing modes.

Table 76. CPU addressing mode overview

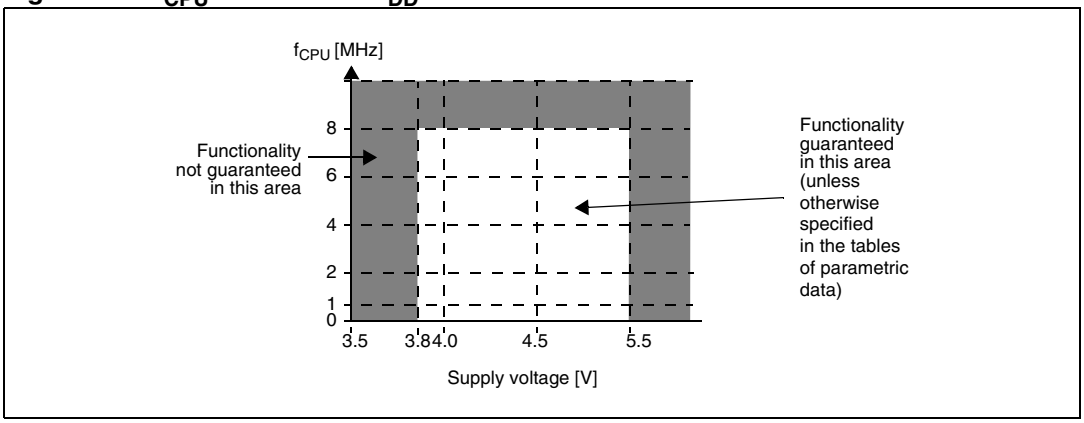
Mode			Syntax	Destination	Pointer address (Hex.)	Pointer size (Hex.)	Length (bytes)
Inherent			nop				+ 0
Immediate			ld A,#$55				+ 1
Short	Direct		ld A,$10	00..FF			+ 1
Long	Direct		ld A,$1000	0000..FFFF			+ 2
No offset	Direct	Indexed	ld A,(X)	00..FF			+ 0
Short	Direct	Indexed	ld A,($10,X)	00..1FE			+ 1
Long	Direct	Indexed	ld A,($1000,X)	0000..FFFF			+ 2
Short	Indirect		ld A,[$10]	00..FF	00..FF	byte	+ 2
Long	Indirect		ld A,[$10.w]	0000..FFFF	00..FF	word	+ 2
Short	Indirect	Indexed	ld A,([$10],X)	00..1FE	00..FF	byte	+ 2
Long	Indirect	Indexed	ld A,([$10.w],X)	0000..FFFF	00..FF	word	+ 2

12.3 Operating conditions

Table 86. Operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
f_{CPU}	Internal clock frequency		0	8	MHz
V_{DD}	Operating voltage (except Flash Write/Erase)		3.8	5.5	V
	Operating Voltage for Flash Write/Erase	V_{PP} = 11.4 to 12.6 V	4.5	5.5	
T_A	Ambient temperature range	1-suffix version	0	70	°C
		5-suffix version	-10	85	
		6-suffix version	-40	85	
		7-suffix version	-40	105	
		3-suffix version	-40	125	

Figure 64. f_{CPU} max versus V_{DD}



Note: Some temperature ranges are only available with a specific package and memory size. Refer to Section 14: Device configuration and ordering information.

Warning: Do not connect 12 V to V_{PP} before V_{DD} is powered on, as this may damage the device.

12.5.2 Flash current consumption

Table 90. Flash current consumption

Symbol	Parameter	Conditions	32 Kbyte Flash		16/8 Kbyte Flash		Unit
			Typ	Max(1)	Typ	Max(1)	
I_{DD}	Supply current in Run mode(2)	f_{OSC} = 2 MHz, f_{CPU} = 1 MHz f_{OSC} = 4 MHz, f_{CPU} = 2 MHz f_{OSC} = 8 MHz, f_{CPU} = 4 MHz f_{OSC} = 16 MHz, f_{CPU} = 8 MHz	1.3 2.0 3.6 7.1	3.0 5.0 8.0 15.0	1 1.4 2.4 4.4	2.3 3.5 5.3 7.0	mA
	Supply current in Slow mode(2)	f_{OSC} = 2 MHz, f_{CPU} = 62.5 kHz f_{OSC} = 4 MHz, f_{CPU} = 125 kHz f_{OSC} = 8 MHz, f_{CPU} = 250 kHz f_{OSC} = 16 MHz, f_{CPU} = 500 kHz	0.6 0.7 0.8 1.1	2.7 3.0 3.6 4.0	0.48 0.53 0.63 0.80	1 1.1 1.2 1.4	
	Supply current in Wait mode(2)	f_{OSC} = 2 MHz, f_{CPU} = 1 MHz f_{OSC} = 4 MHz, f_{CPU} = 2 MHz f_{OSC} = 8 MHz, f_{CPU} = 4 MHz f_{OSC} = 16 MHz, f_{CPU} = 8 MHz	0.8 1.2 2.0 3.5	3.0 4.0 5.0 7.0	0.6 0.9 1.3 2.3	1.8 2.2 2.6 3.6	
	Supply current in Slow Wait mode(2)	f_{OSC} = 2 MHz, f_{CPU} = 62.5 kHz f_{OSC} = 4 MHz, f_{CPU} = 125 kHz f_{OSC} = 8 MHz, f_{CPU} = 250 kHz f_{OSC} = 16 MHz, f_{CPU} = 500 kHz	580 650 770 1050	1200 1300 1800 2000	430 470 530 660	950 1000 1050 1200	µA
	Supply current in Halt mode(3)	-40°C ≤ T_A ≤ +85°C	<1	10	<1	10	
		-40°C ≤ T_A ≤ +125°C	5	50	<1	50	
	Supply current in Active-halt mode(4)	f_{OSC} = 2 MHz f_{OSC} = 4 MHz f_{OSC} = 8 MHz f_{OSC} = 16 MHz	365 380 410 500	475 500 550 650	315 330 360 460	425 450 500 600	

1. Data based on characterization results, tested in production at V_{DD} max. and f_{CPU} max.
2. Measurements are done in the following conditions:
   - Program executed from RAM, CPU running with RAM access. The increase in consumption when executing from Flash is 50%.
   - All I/O pins in input mode with a static value at V_{DD} or V_{SS} (no load)
   - All peripherals in reset state
   - LVD disabled
   - Clock input (OSC1) driven by external square wave
   - In Slow and Slow Wait modes, f_{CPU} is based on f_{OSC} divided by 32
   - To obtain the total current consumption of the device, add the clock source (*Section 12.6.3*) and the peripheral power consumption (*Section 12.5.4*).
3. All I/O pins in push-pull 0 mode (when applicable) with a static value at V_{DD} or V_{SS} (no load), LVD disabled. Data based on characterization results, tested in production at V_{DD} max. and f_{CPU} max.
4. Data based on characterization results, not tested in production. All I/O pins in push-pull 0 mode (when applicable) with a static value at V_{DD} or V_{SS} (no load); clock input (OSC1) driven by external square wave, LVD disabled. To obtain the total current consumption of the device, add the clock source consumption (*Section 12.6.3*).

12.5.3 Supply and clock managers

The previous current consumption specified for the ST7 functional operating modes over temperature range does not take into account the clock source current consumption. To obtain the total device consumption, the two current values must be added (except for Halt mode).

Table 91. Oscillators, PLL and LVD current consumption

Symbol	Parameter	Conditions	Typ	Max	Unit
$I_{DD(RCINT)}$	Supply current of internal RC oscillator		625		µA
$I_{DD(RES)}$	Supply current of resonator oscillator(1)(2)		see Section 12.6.3 on page 150		
$I_{DD(PLL)}$	PLL supply current	V_{DD} = 5V	360		
$I_{DD(LVD)}$	LVD supply current		150	300	

1. Data based on characterization results done with the external components specified in Section 12.6.3, not tested in production.
2. As the oscillator is based on a current source, the consumption does not depend on the voltage.

12.5.4 On-chip peripherals

Table 92. On-chip peripherals current consumption

Symbol	Parameter	Conditions	Typ	Unit
$I_{DD(TIM)}$	16-bit timer supply current(1)	T_A = 25 °C, f_{CPU} = 4 MHz, V_{DD} = 5.0 V	50	µA
$I_{DD(SPI)}$	SPI supply current(2)		400	
$I_{DD(SCI)}$	SCI supply current(3)			
$I_{DD(ADC)}$	ADC supply current when converting(4)			

1. Data based on a differential I_{DD} measurement between reset configuration (timer counter running at $f_{CPU}/4$) and timer counter stopped (only TIMD bit set). Data valid for one timer.
2. Data based on a differential I_{DD} measurement between reset configuration (SPI disabled) and a permanent SPI master communication at maximum speed (data sent equal to 55h). This measurement includes the pad toggling consumption.
3. Data based on a differential I_{DD} measurement between SCI low power state (SCID = 1) and a permanent SCI data transmit sequence.
4. Data based on a differential I_{DD} measurement between reset configuration and continuous A/D conversions.

12.6 Clock and timing characteristics

Subject to general operating conditions for V_{DD}, f_{CPU}, and T_A.

12.6.1 General timings

Table 93. General timings

Symbol	Parameter	Conditions	Min	Typ(1)	Max	Unit
$t_{c(INST)}$	Instruction cycle time		2	3	12	t_{CPU}
		f_{CPU} = 8 MHz	250	375	1500	ns
$t_{v(IT)}$	Interrupt reaction time $t_{v(IT)} = \Delta t_{c(INST)} + 10$(2)		10		22	t_{CPU}
		f_{CPU} = 8 MHz	1.25		2.75	µs

1. Data based on typical application software.
2. Time measured between interrupt event and interrupt vector fetch. $\Delta t_{c(INST)}$ is the number of t_{CPU} cycles needed to finish the current instruction execution.

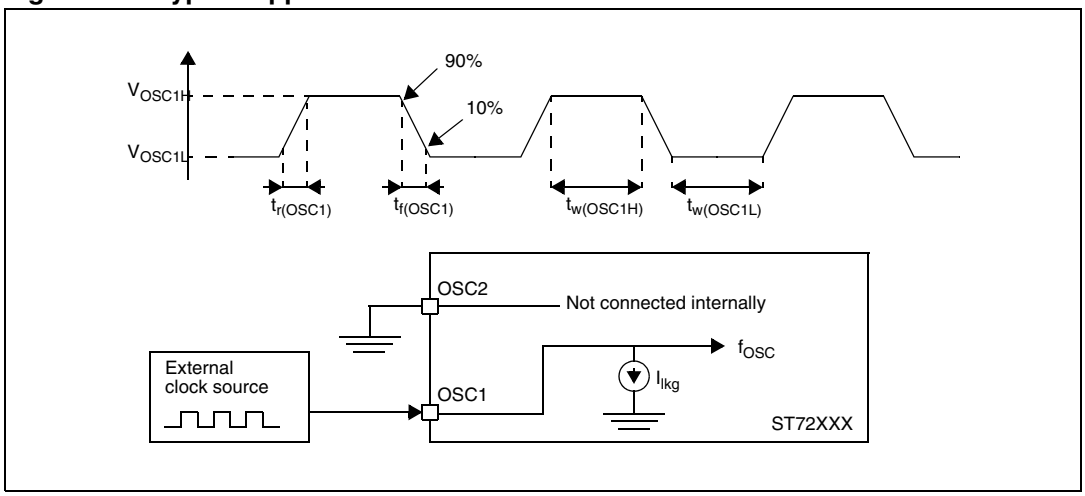
12.6.2 External clock source

Table 94. External clock source

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{OSC1H}	OSC1 input pin high level voltage	See *Figure 65.*	V_{DD}-1		V_{DD}	V
V_{OSC1L}	OSC1 input pin low level voltage		V_{SS}		V_{SS}+1	
$t_{w(OSC1H)}$ $t_{w(OSC1L)}$	OSC1 high or low time(1)		5			ns
$t_{r(OSC1)}$ $t_{f(OSC1)}$	OSC1 rise or fall time(1)				15	
I_{lkg}	OSC1 input leakage current	$V_{SS} \le V_{IN} \le V_{DD}$			±1	µA

1. Data based on design simulation and/or technology characteristics, not tested in production.

Figure 65. Typical application with an external clock source



12.6.3 Crystal and ceramic resonator oscillators

The ST7 internal clock can be supplied with four different crystal/ceramic resonator oscillators. All the information given in this paragraph are based on characterization results with specified typical external components. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and start-up stabilization time. Refer to the crystal/ceramic resonator manufacturer for more details (frequency, package, accuracy...).

8/16 Kbyte Flash and ROM devices

Table 95. Crystal and ceramic resonator oscillators (8/16 Kbyte Flash and ROM devices)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{OSC}	Oscillator frequency(1)	LP: low power oscillator MP: medium power oscillator MS: medium speed oscillator HS: high speed oscillator	1 >2 >4 >8		2 4 8 16	MHz
R_F	Feedback resistor(2)		20		40	kΩ
C_{L1} C_{L2}	Recommended load capacitance versus equivalent serial resistance of the crystal or ceramic resonator (R_S)(3)	R_S = 200 Ω LP oscillator R_S = 200 Ω MP oscillator R_S = 200 Ω MS oscillator R_S = 100 Ω HS oscillator	22 22 18 15		56 46 33 33	pF
i_2	OSC2 driving current	V_{DD} = 5V, V_{IN} = V_{SS} LP oscillator MP oscillator MS oscillator HS oscillator		 80 160 310 610	 150 250 460 910	µA

1. The oscillator selection can be optimized in terms of supply current using an high quality resonator with small R_S value. Refer to crystal/ceramic resonator manufacturer for more details.
2. Data based on characterization results, not tested in production. The relatively low value of the RF resistor, offers a good protection against issues resulting from use in a humid environment, due to the induced leakage and the bias condition change. However, it is recommended to take this point into account if the microcontroller is used in tough humidity conditions.
3. For C_{L1} and C_{L2} it is recommended to use high-quality ceramic capacitors in the 5 pF to 25 pF range (typ.) designed for high-frequency applications and selected to match the requirements of the crystal or resonator. C_{L1} and C_{L2}, are usually the same size. The crystal manufacturer typically specifies a load capacitance which is the series combination of C_{L1} and C_{L2}. PCB and MCU pin capacitance must be included when sizing C_{L1} and C_{L2} (10 pF can be used as a rough estimate of the combined pin and board capacitance).

$\overline{\text{RESET}}$ pin protection when LVD is enabled

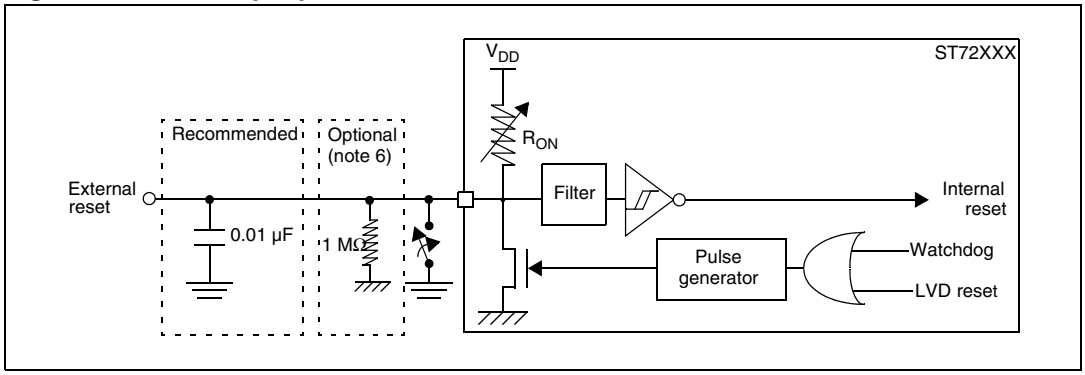
When the LVD is enabled, it is recommended to protect the $\overline{\text{RESET}}$ pin as shown in *Figure 78* and follow these guidelines:

1. The reset network protects the device against parasitic resets.
2. The output of the external reset circuit must have an open-drain output to drive the ST7 reset pad. Otherwise the device can be damaged when the ST7 generates an internal reset (LVD or watchdog).
3. Whatever the reset source is (internal or external), the user must ensure that the level on the $\overline{\text{RESET}}$ pin can go below the V_{IL} max. level specified in *Section 12.10.1*. Otherwise the reset will not be taken into account internally.
4. Because the reset circuit is designed to allow the internal RESET to be output in the $\overline{\text{RESET}}$ pin, the user must ensure that the current sunk on the $\overline{\text{RESET}}$ pin (by an external pull-up for example) is less than the absolute maximum value specified for $I_{INJ(RESET)}$ in *Section 12.2.2 on page 143*.
5. When the LVD is enabled, it is mandatory not to connect a pull-up resistor. A 10nF pull-down capacitor is recommended to filter noise on the reset line.
6. In case a capacitive power supply is used, it is recommended to connect a 1M ohm pull-down resistor to the $\overline{\text{RESET}}$ pin to discharge any residual voltage induced by this capacitive power supply (this will add 5 µA to the power consumption of the MCU).

Tips when using the LVD:

- Check that all recommendations related to reset circuit have been applied (see section above)
- Check that the power supply is properly decoupled (100 nF + 10 µF close to the MCU). Refer to AN1709. If this cannot be done, it is recommended to put a 100 nF + 1 M Ohm pull-down on the $\overline{\text{RESET}}$ pin.
- The capacitors connected on the $\overline{\text{RESET}}$ pin and also the power supply are key to avoiding any start-up marginality. In most cases, steps 1 and 2 above are sufficient for a robust solution. Otherwise: Replace 10 nF pull-down on the $\overline{\text{RESET}}$ pin with a 5 µF to 20 µF capacitor.

Figure 78. $\overline{\text{RESET}}$ pin protection when LVD is enabled



12.13.1 Analog power supply and reference pins

Depending on the MCU pin count, the package may feature separate V_{AREF} and V_{SSA} analog power supply pins. These pins supply power to the A/D converter cell and function as the high and low reference voltages for the conversion. In some packages, V_{AREF} and V_{SSA} pins are not available (refer to *Section 2 on page 15*). In this case the analog supply and reference pads are internally bonded to the V_{DD} and V_{SS} pins.

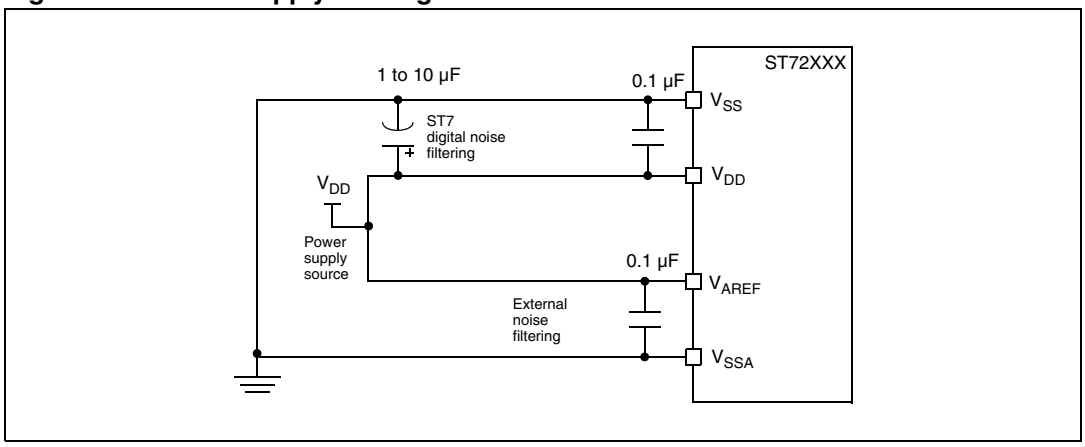
Separation of the digital and analog power pins allow board designers to improve A/D performance. Conversion accuracy can be impacted by voltage drops and noise in the event of heavily loaded or badly decoupled power supply lines (see *Section 12.13.2: General PCB design guidelines*).

12.13.2 General PCB design guidelines

To obtain best results, some general design and layout rules should be followed when designing the application PCB to shield the noise-sensitive, analog physical interface from noise-generating CMOS logic signals.

- Use separate digital and analog planes. The analog ground plane should be connected to the digital ground plane via a single point on the PCB.
- Filter power to the analog power planes. It is recommended to connect capacitors, with good high frequency characteristics, between the power and ground lines, placing 0.1µF and optionally, if needed 10 pF capacitors as close as possible to the ST7 power supply pins and a 1 to 10 µF capacitor close to the power source (see *Figure 87*).
- The analog and digital power supplies should be connected in a star network. Do not use a resistor, as V_{AREF} is used as a reference voltage by the A/D converter and any resistance would cause a voltage drop and a loss of accuracy.
- Properly place components and route the signal traces on the PCB to shield the analog inputs. Analog signals paths should run over the analog ground plane and be as short as possible. Isolate analog signals from digital signals that may switch while the analog inputs are being sampled by the A/D converter. Do not toggle digital outputs on the same I/O port as the A/D input being converted.

Figure 87. Power supply filtering



13.3 Thermal characteristics

Table 118. Thermal characteristics

Symbol	Ratings	Value	Unit
R_{thJA}	Package thermal resistance (junction to ambient): LQFP44 10x10 LQFP32 7x7 DIP42 600mil SDIP32 200mil	 52 70 55 50	°C/W
P_D	Power dissipation(1)	500	mW
T_{Jmax}	Maximum junction temperature(2)	150	°C

1. The maximum power dissipation is obtained from the formula $P_D = (T_J - T_A) / R_{thJA}$. The power dissipation of an application can be defined by the user with the formula: $P_D = P_{INT} + P_{PORT}$ where P_{INT} is the chip internal power ($I_{DD} \times V_{DD}$) and P_{PORT} is the port power dissipation depending on the ports used in the application.
2. The maximum chip-junction temperature is based on technology characteristics.

ST72324Bxx MICROCONTROLLER OPTION LIST
(Last update: March 2009)

Customer: . . . . . .
Address: . . . . . .
. . . . . .
Contact: . . . . . .
Phone No: . . . . . .
Reference/ROM Code* : . . . . . .
*The ROM code name is assigned by STMicroelectronics.
ROM code must be sent in .S19 format. .Hex extension cannot be processed.

Device type/memory size/package (check only one option):

ROM DEVICE:	32K	16K	8K
LQFP32:	[ ]	[ ]	[ ]
DIP32:	[ ]	[ ]	[ ]
LQFP44 :	[ ]	[ ]	[ ]
DIP42:	[ ]	[ ]	[ ]
DIE FORM:	**32K**	**16K**	**8K**
32-pin:	[ ]	[ ]	[ ]
44-pin:	[ ]	[ ]	[ ]

Conditioning (check only one option):

Packaged product	Die product (dice tested at 25 °C only)
LQFP: [ ] Tape & reel [ ] Tray	[ ] Tape & Reel
DIP: [ ] Tube	[ ] Inked wafer
	[ ] Sawn wafer on sticky foil

Power supply range: [ ] 3.8 to 5.5 V
Temp. range (do not check for die product).

[ ] 0 °C to +70 °C
[ ] -10 °C to +85 °C
[ ] -40 °C to +85 °C
[ ] -40 °C to +105 °C
[ ] -40 °C to +125 °C

Special marking: [ ] No [ ] Yes "_ _ _ _ _ _ _ _ _ _ " (LQFP32 7 char., other pkg. 10 char. max)
Authorized characters are letters, digits, '.', '-', '/' and spaces only.

Clock source selection:
[ ] Resonator: [ ] LP: Low power resonator (1 to 2 MHz)
[ ] MP: Medium power resonator (2 to 4 MHz)
[ ] MS: Medium speed resonator (4 to 8 MHz)
[ ] HS: High speed resonator (8 to 16 MHz)
[ ] Internal RC
[ ] External clock

PLL [ ] Disabled [ ] Enabled
LVD Reset [ ] Disabled [ ] High threshold [ ] Med. threshold [ ] Low threshold
Reset Delay [ ] 256 Cycles [ ] 4096 Cycles

Watchdog selection: [ ] Software activation [ ] Hardware activation
Watchdog Reset on Halt: [ ] Reset [ ] No Reset

Readout protection: [ ] Disabled [ ] Enabled

Date . . . . . .
Signature . . . . . .

Caution: The readout protection binary value is inverted between ROM and Flash products. The option byte checksum will differ between ROM and Flash.